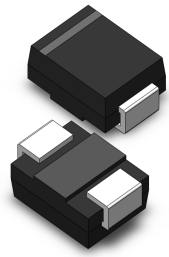
EC11FS4

SUPER FAST RECOVERY RECTIFIER DIODES

VOLTAGE RANGE: 400V
CURRENT: 1.0 A



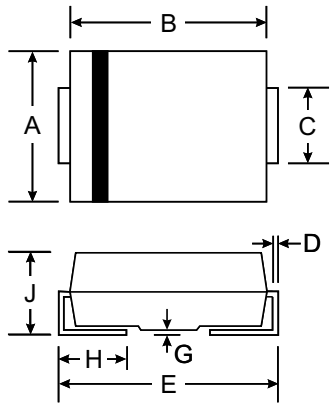
Features

- Miniature Size,Surface Mount Device
- Low Forward Voltage Drop
- High Surge Capability
- Low Power Loss,High Efficiency
- Ultra-Fast Recovery
- Packaged in 12mm Tape and Reel
- Not Rolling During Assembly

Mechanical Data

- Case: SMB/DO-214AA, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)

RoHS COMPLIANT



SMB(DO-214AA)		
Dim	**Min**	**Max**
A	3.30	3.94
B	4.06	4.70
C	1.91	2.21
D	0.15	0.31
E	5.00	5.59
G	0.10	0.20
H	0.76	1.52
J	2.00	2.62
All Dimensions in mm		

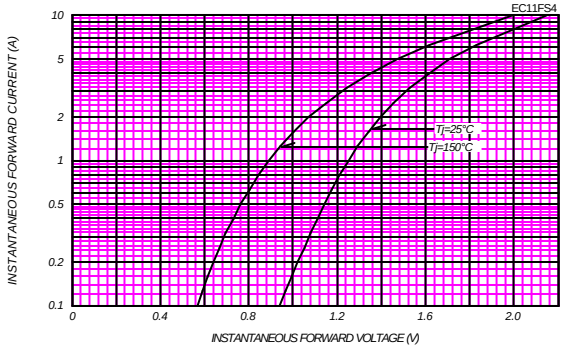
Maximum Ratings @ T_A = 25°C unless otherwise specified

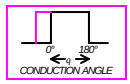
Characteristic	Symbol	EC11FS4	Unit
RepetitivePeak Reverse Voltage	VRRM	400	V
Non-repetitive Peak Reverse Voltage	VRSM	440	V
Average Rectified Forward Current 50Hz Half Sine Wave Resistive Load	IO	0.76 1.0	A
R.M.S.Forward Current	IF(RMS)	1.57	A
Surge Forward Current 50Hz Half Sine Wave,Icycle,Non-repetitive	IFSM	20	A
Operating Junction Temperature Range	Tjw	-40 to +150	°C
Storage Temperature Range	Tstg	-40 to +150	°C

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Peak Reverse Current Tj= 25°C, V RM = V RRM	IRM	-	-	20	μA
Peak Forward Voltage Tj= 25 °C, I FM = 0.8A	VFM	-	-	1.25	V
Reverse Recovery Time I FM =1A, -di/dt= 50A/ s, Ta = 25°C	trr	-	-	30	ns
Thermal Resistance Junction to Ambient *1	Rth(j-a)	-	-	157	°C /W
*2		-	-	108	

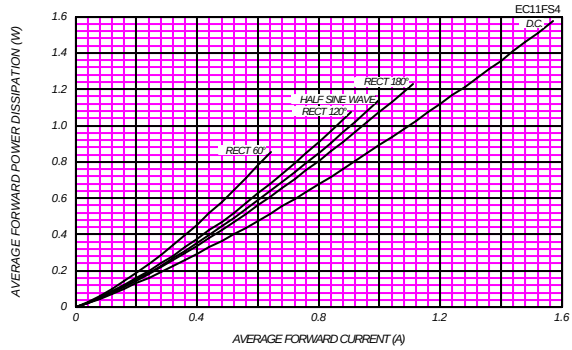
1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm,Both Sides)
2 Alumina Substrate Mounted (Soldering Lands=2x2mm,Both Sides)

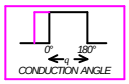
FORWARD CURRENT VS. VOLTAGE





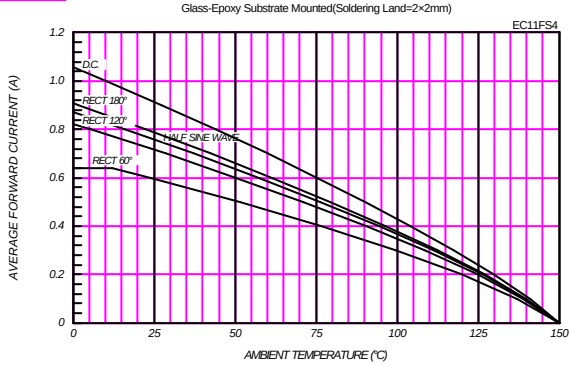
AVERAGE FORWARD POWER DISSIPATION

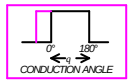




AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

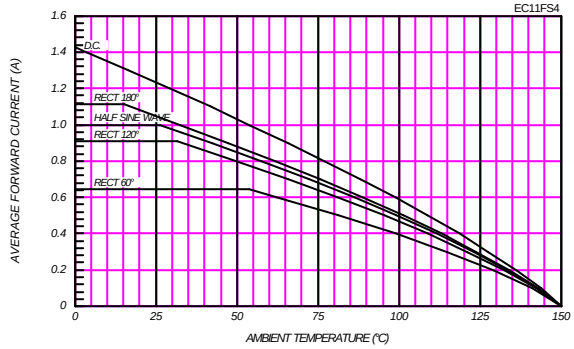
Glass-Epoxy Substrate Mounted(Soldering Land=2×2mm)





AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Alumina Substrate Mounted(Soldering Land=2×2mm)



SURGE CURRENT RATINGS

f=50Hz,Half Sine Wave,Non-Repetitive,No Load